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PATENT  
790001-2004

2813

#5  
2-21-02  
Pham

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

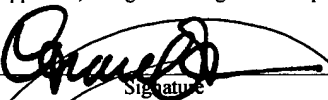
Applicants : Yano et al.  
U.S. Serial No. : 09/870,085  
Filing Date : May 30, 2001  
For : ***Manufacturing Method of Semiconductor Device***  
Examiner: : Thanhha Pham  
Group Art Unit : 2813

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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231, on January 18, 2002.

Grace L. Pan, Reg. No. 39,440

Name of Applicant, Assignee or Registered Representative



Signature

January 18, 2002  
Date of Signature

**RESPONSE**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the December 20, 2001 Office Action, which sets a one-month period for response, Applicants provisionally elect, with traverse, the invention of Species A, claims 1 to 6, directed to a method of manufacturing a semiconductor device comprising a step of selectively grinding or polishing the peripheral portion and the beveled portion of the side of the main surface of target substrate including the semiconductor substrate for further prosecution, without prejudice.